

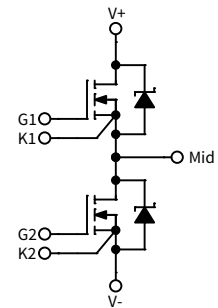
CAS300M17BM2

1700 V, 8.0 mΩ, Silicon Carbide, Half-Bridge Module

V_{DS}	1700 V
I_{DS}	300 A

Technical Features

- Industry Standard 62 mm Footprint
- Ultra Low Loss, High-Frequency Operation
- Zero Reverse Recovery from Diodes
- Zero Turn-off Tail Current from MOSFET
- Normally-off, Fail-safe Device Operation
- Copper Baseplate and Aluminum Nitride Insulator



Applications

- HF Resonant Converters/Inverters
- Solar and Wind Inverters
- UPS and SMPS
- Motor Drive
- Traction

System Benefits

- Enables Compact and Lightweight Systems
- High Efficiency Operation
- Mitigates Over-voltage Protection
- Reduced Thermal Requirements
- Reduced System Cost

Key Parameters

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions	Note
Drain-Source Voltage	V _{DS}			1700	V	T _C = 25 °C	
Gate-Source Voltage, Maximum Value	V _{GS(max)}	-10		+25		Transient	Note 1 Fig. 33
Gate-Source Voltage, Recommended	V _{GS(op)}		-5/+20			Static	
DC Continuous Drain Current	I _D		325		A	V _{GS} = 20 V, T _C = 25 °C, T _{VJ} ≤ 150 °C	Notes 2, 3 Fig. 21
			225			V _{GS} = 20 V, T _C = 90 °C, T _{VJ} ≤ 150 °C	
DC Source-Drain Current (Schottky Diode)	I _{SD(SD)}		556			V _{GS} = -5 V, T _C = 25 °C, T _{VJ} ≤ 150 °C	
Pulsed Drain-Source Current	I _{DM}		900			t _{pmax} limited by T _{VJmax} V _{GS} = 20 V, T _C = 25 °C	
Power Dissipation	P _D		1866		W	T _C = 25 °C, T _{VJ} ≤ 150 °C	Note 4 Fig. 21
Virtual Junction Temperature	T _{VJ(op)}	-40		150	°C	Operation	

Note (1): Recommended turn-on gate voltage is 20 V with ±5 % regulation tolerance

Note (2): Current limit at T_C = 90 °C calculated by I_{D(max)} = √(P_D/R_{DS(typ)}(T_{VJ(max)} - T_{D(max)}))

Note (3): Verified by design

Note (4): P_D = (T_{VJ} - T_C)/R_{TH(JC,typ)}

MOSFET Characteristics (Per Position) ($T_{VJ} = 25\text{ }^{\circ}\text{C}$ Unless Otherwise Specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions	Note
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	1700			V	$V_{GS} = 0\text{ V}, I_{DS} = 2\text{ mA}$	Fig. 29
Gate Threshold Voltage	$V_{GS(th)}$	1.8	2.5			$V_{DS} = V_{GS}, I_{DS} = 104\text{ mA}$	Fig. 7
Zero Gate Voltage Drain Current	I_{DSS}		0.7	2	mA	$V_{GS} = 0\text{ V}, V_{DS} = 1700\text{ V}$	
			1.5	4		$V_{GS} = 0\text{ V}, V_{DS} = 1700\text{ V}, T_{VJ} = 150\text{ }^{\circ}\text{C}$	
Gate-Source Leakage Current	I_{GSS}		1	600	nA	$V_{GS} = 25\text{ V}, V_{DS} = 0\text{ V}$	
Drain-Source On-State Resistance (MOSFET Only)	$R_{DS(on)}$		8.0	10.0	m Ω	$V_{GS} = 20\text{ V}, I_D = 300\text{ A}$	Fig. 4
			16.2	20.0		$V_{GS} = 20\text{ V}, I_D = 300\text{ A}, T_{VJ} = 150\text{ }^{\circ}\text{C}$	Fig. 5 Fig. 6
Transconductance	g_{fs}		133		S	$V_{DS} = 20\text{ V}, I_D = 300\text{ A}$	Fig. 8
			131			$V_{DS} = 20\text{ V}, I_D = 300\text{ A}, T_{VJ} = 150\text{ }^{\circ}\text{C}$	
Turn-On Switching Energy	E_{ON}		13.0		mJ	$V_{DD} = 900\text{ V}, I_D = 300\text{ A},$ $V_{GS} = -5\text{ V}/+20\text{ V},$ $R_{G(ON)} = 2.5\text{ }\Omega, R_{G(OFF)} = 2.5\text{ }\Omega,$ $L = 77\text{ }\mu\text{H}$ $T_{VJ} = 150\text{ }^{\circ}\text{C}$ Note: IEC 60747-8-4 Definitions	Fig. 22
Turn-Off Switching Energy	E_{OFF}		10.0				
Internal Gate Resistance	$R_{G(int)}$		3.7		Ω	$f = 100\text{ kHz}, V_{AC} = 25\text{ mV}$	
Input Capacitance	C_{iss}		20		nF	$V_{DS} = 1000\text{ V}, V_{AC} = 25\text{ mV}$ $f = 100\text{ kHz}$	Fig. 16 Fig. 17
Output Capacitance	C_{oss}		2.5				
Reverse Transfer Capacitance	C_{rss}		80				
Gate to Source Charge	Q_{GS}		273		nC	$V_{DS} = 900\text{ V}, V_{GS} = -5\text{ V}/+20\text{ V},$ $I_D = 300\text{ A},$ Per JEDED24 pg 27	Fig. 15
Gate to Drain Charge	Q_{GD}		324				
Total Gate Charge	Q_G		1076				
Turn-On Delay Time	$t_{d(on)}$		105		ns	$V_{DD} = 900\text{ V}, V_{GS} = -5\text{ V}/+20\text{ V},$ $I_D = 300\text{ A}, R_{G(ext)} = 2.5\text{ }\Omega,$ Timing Relative to V_{DS} Note: IEC 60747-8-4, pg 83 Inductive Load	Fig. 23
Rise Time	t_r		72				
Turn-Off Delay Time	$t_{d(off)}$		211				
Fall Time	t_f		56				
FET Thermal Resistance, Junction to Case	R_{th-JCM}		0.067	0.071	$^{\circ}\text{C}/\text{W}$		Fig. 27



Diode Characteristics (Per Position) ($T_{VJ} = 25\text{ }^{\circ}\text{C}$ Unless Otherwise Specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions	Note
Body Diode Forward Voltage	V_{SD}		1.7	2.0	V	$V_{GS} = 0\text{ V}, I_{SD} = 300\text{ A}$	Fig. 10 Fig. 11
			2.2	2.5		$V_{GS} = 0\text{ V}, I_{SD} = 300\text{ A}, T_{VJ} = 150\text{ }^{\circ}\text{C}$	
Total Capacitive Charge	Q_C		4.4		μC	$I_{SD} = 300\text{ A}, V_{DS} = 900\text{ V}, T_{VJ} = 25\text{ }^{\circ}\text{C},$ $di_{SD}/dt = 9\text{ kA}/\mu\text{s}, V_{GS} = -5\text{ V}$	
DIODE Thermal Resistance, Junction to Case	R_{th-JCD}		0.060	0.065	$^{\circ}\text{C}/\text{W}$		Fig. 28

Module Physical Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Stray Inductance	L_{Stray}		15		nH	Between Terminals 2 & 3
Case Temperature	T_C	-40		125	$^{\circ}\text{C}$	
Mounting Torque	M_S		5.0		N-m	To Heatsink and Terminals
Weight	W		300		g	
Case Isolation Voltage	V_{Isol}	5.0			kV	AC, 50 Hz, 1 minute
Clearance Distance		9			mm	Terminal to Terminal
Creepage Distance		30				Terminal to Terminal
		40				Terminal to Baseplate



Typical Performance

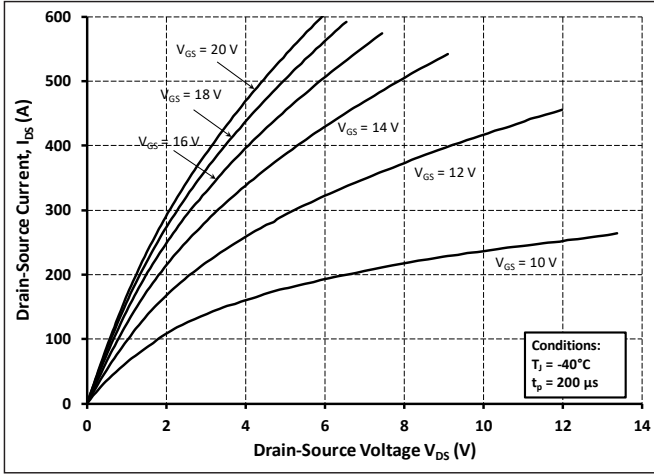


Figure 1. Output Characteristics for $T_{Vj} = 40\text{ }^{\circ}\text{C}$

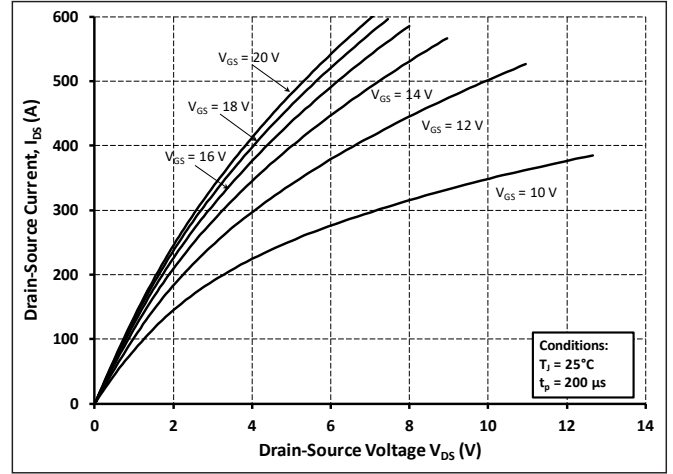


Figure 2. Output Characteristics for $T_{Vj} = 25\text{ }^{\circ}\text{C}$

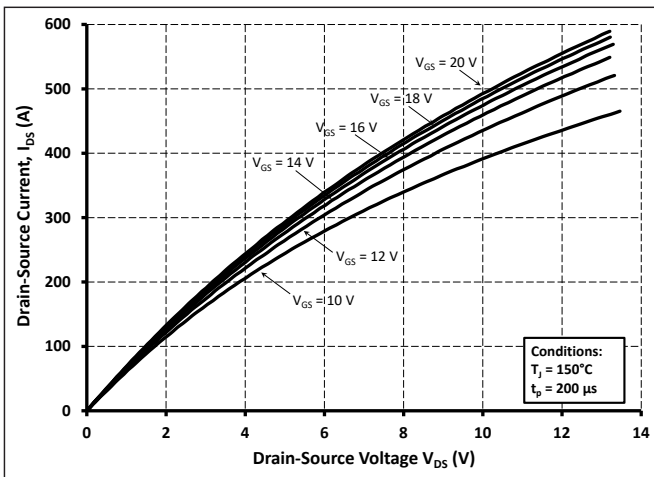


Figure 3. Output Characteristics for $T_{Vj} = 150\text{ }^{\circ}\text{C}$

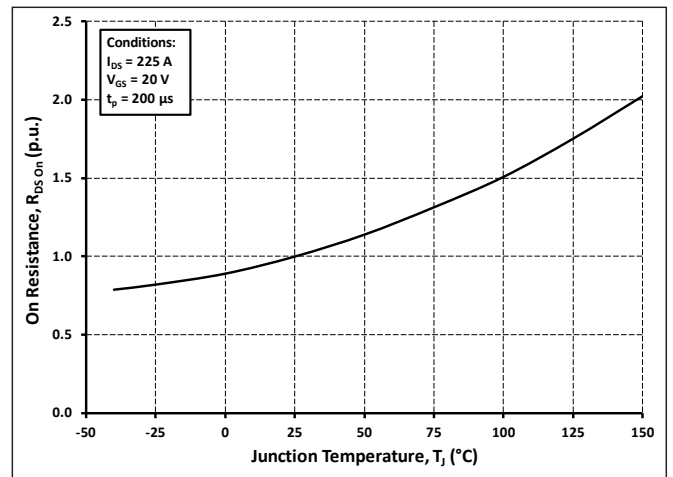


Figure 4. Normalized On-Resistance vs. Temperature

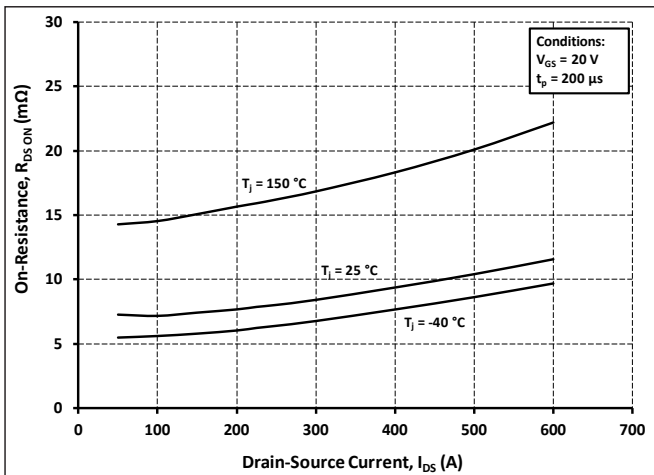


Figure 5. On-Resistance vs. Drain Current For Various Temperatures

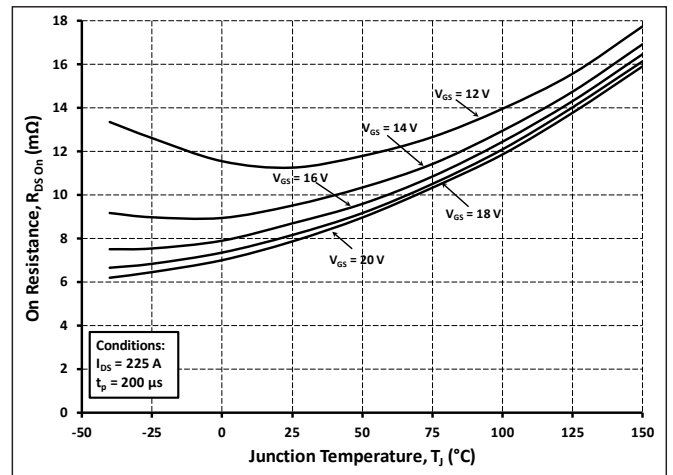


Figure 6. On-Resistance vs. Temperature for Various Gate-Source Voltage



Typical Performance

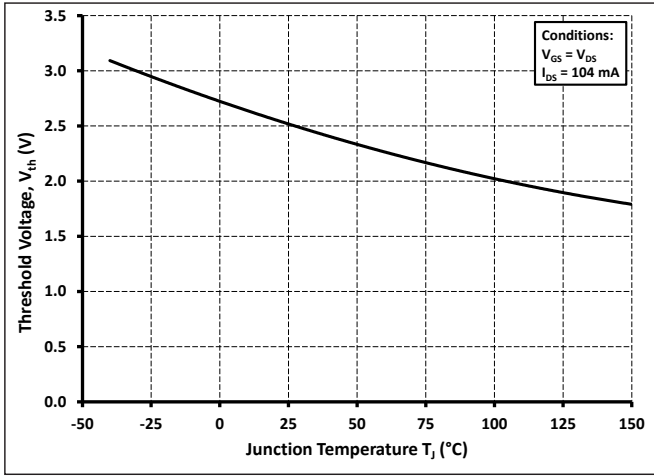


Figure 7. Threshold Voltage vs. Temperature

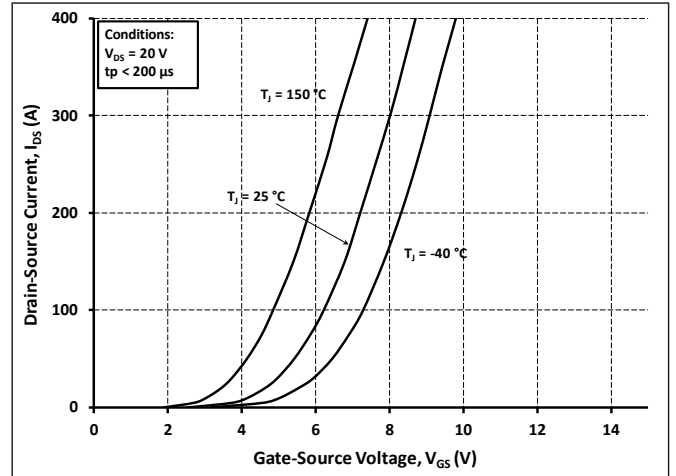


Figure 8. Transfer Characteristic for Various Junction Temperatures

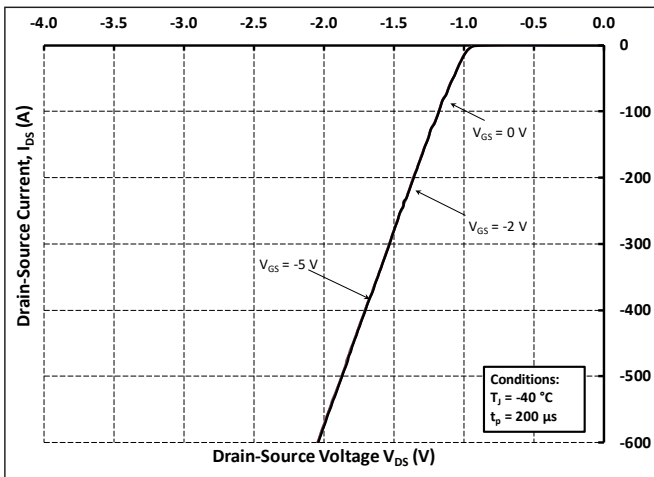


Figure 9. Diode Characteristic at $T_{VJ} = -40^\circ\text{C}$

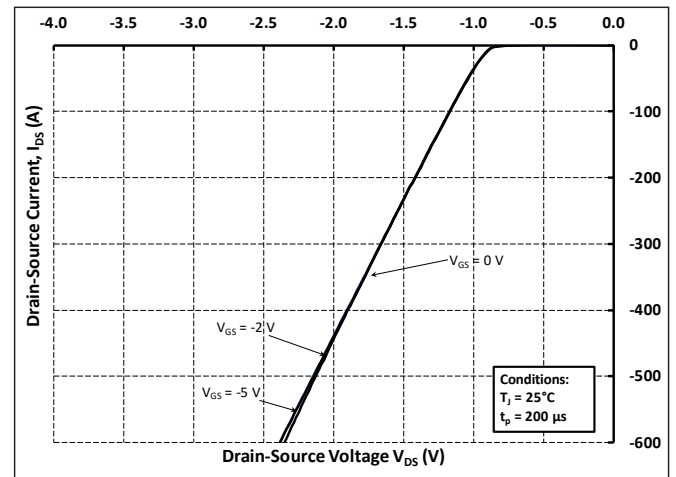


Figure 10. Diode Characteristic at $T_{VJ} = 25^\circ\text{C}$

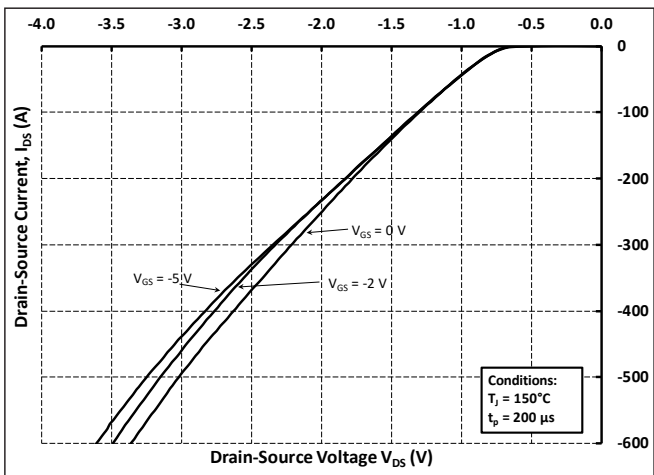


Figure 11. Diode Characteristic at $T_{VJ} = 150^\circ\text{C}$

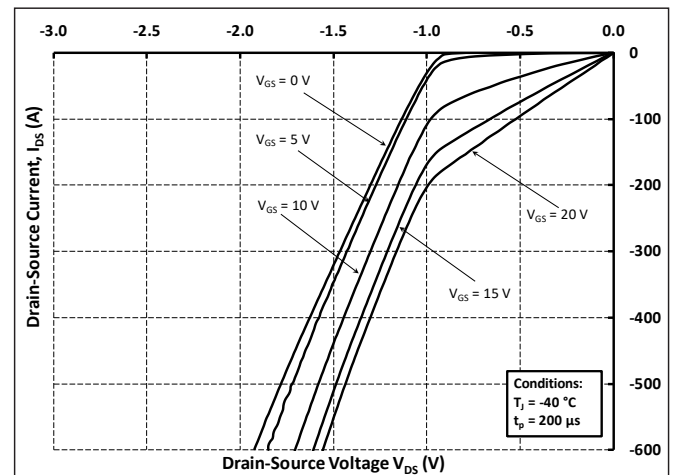


Figure 12. 3rd Quadrant Characteristic at $T_{VJ} = -40^\circ\text{C}$



Typical Performance

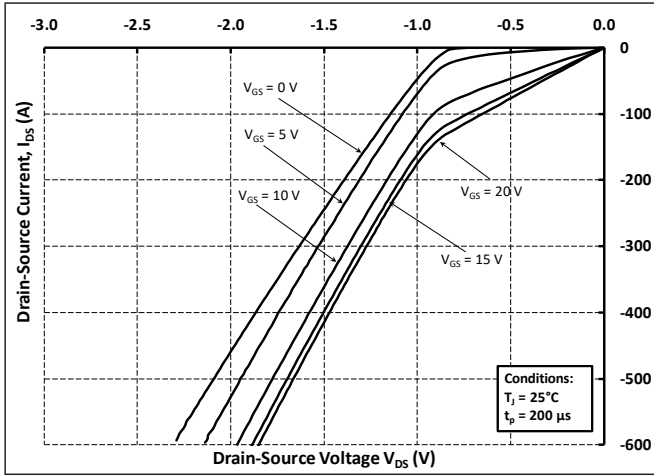


Figure 13. 3rd Quadrant Characteristic at $T_{j} = 25^\circ\text{C}$

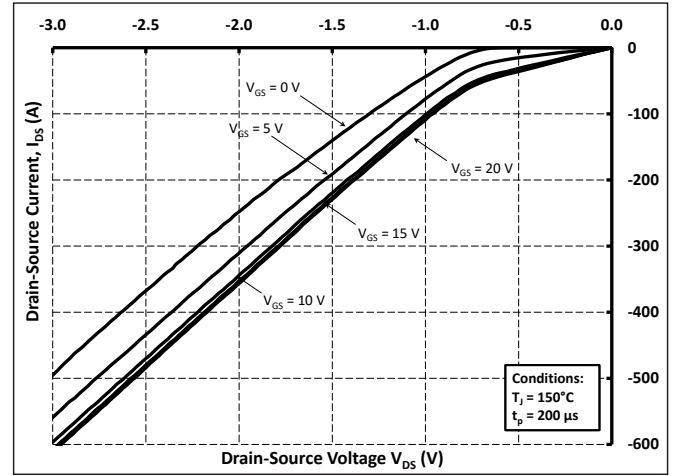


Figure 14. 3rd Quadrant Characteristic at $T_{j} = 150^\circ\text{C}$

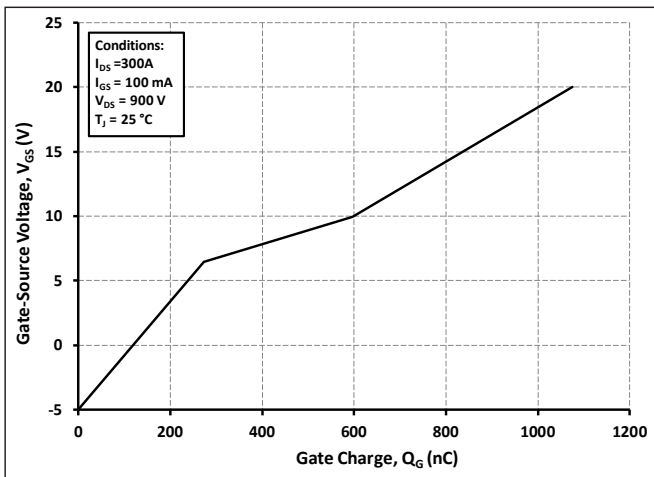


Figure 15. Gate Charge Characteristics

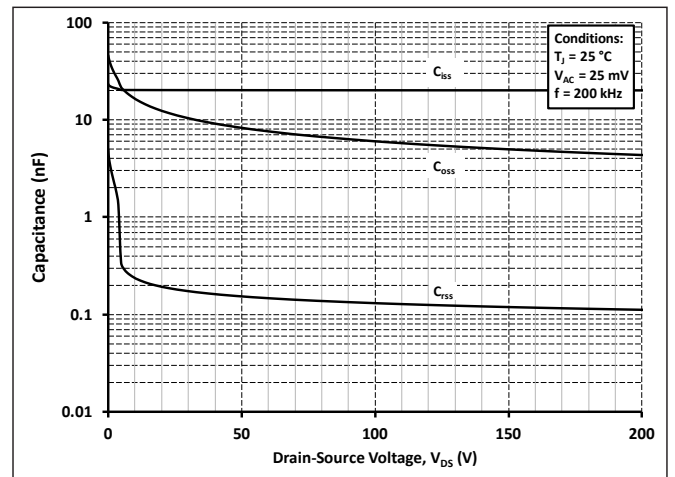


Figure 16. Capacitances vs. Drain-Source Voltage (0 - 200 V)

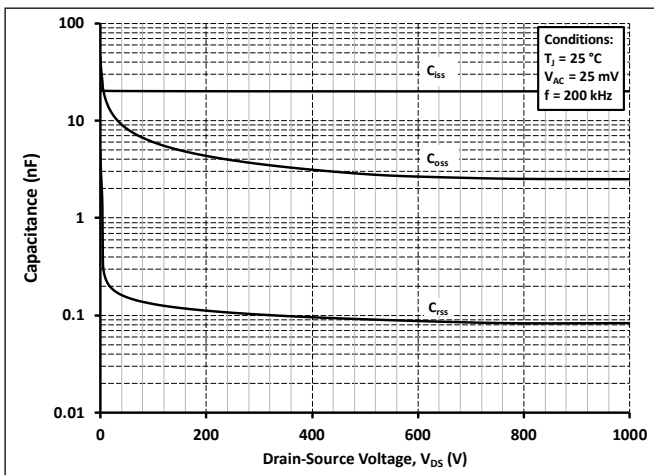


Figure 17. Capacitances vs. Drain-Source Voltage (0 - 1 kV)

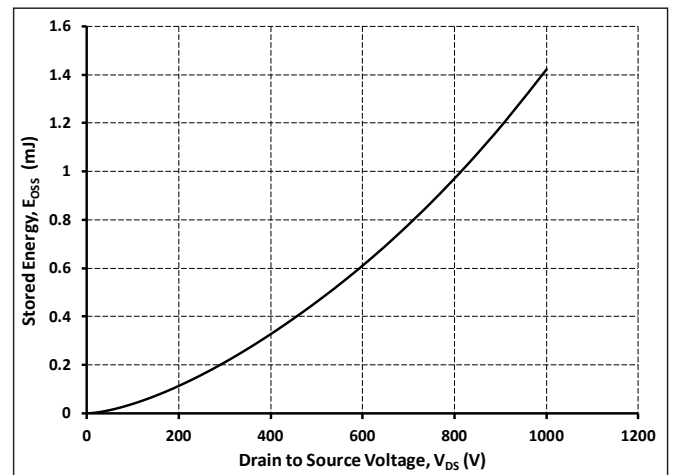


Figure 18. Output Capacitor Stored Energy



Typical Performance

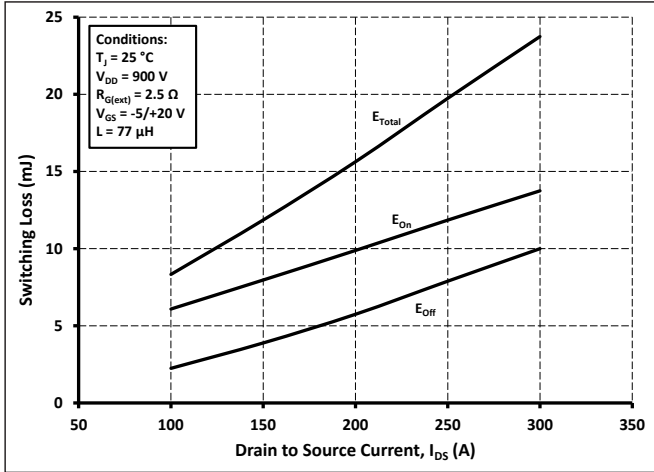


Figure 19. Inductive Switching Energy vs. Drain Current For $V_{DS} = 900\text{ V}$, $R_G = 2.5\text{ }\Omega$

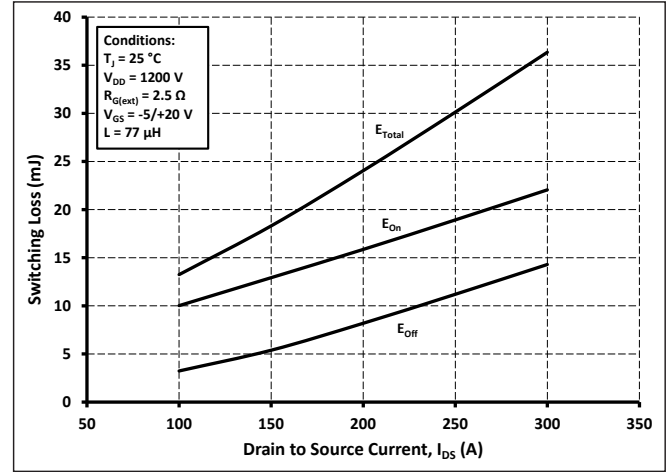


Figure 20. Inductive Switching Energy vs. Drain Current For $V_{DS} = 1200\text{ V}$, $R_G = 2.5\text{ }\Omega$

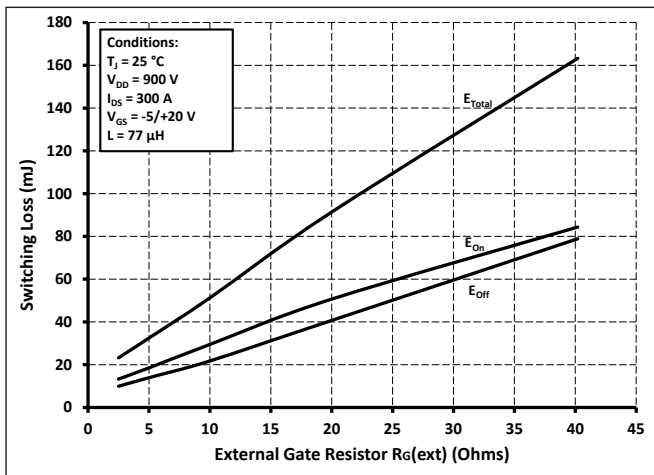


Figure 21. Inductive Switching Energy vs. $R_{G(\text{ext})}$

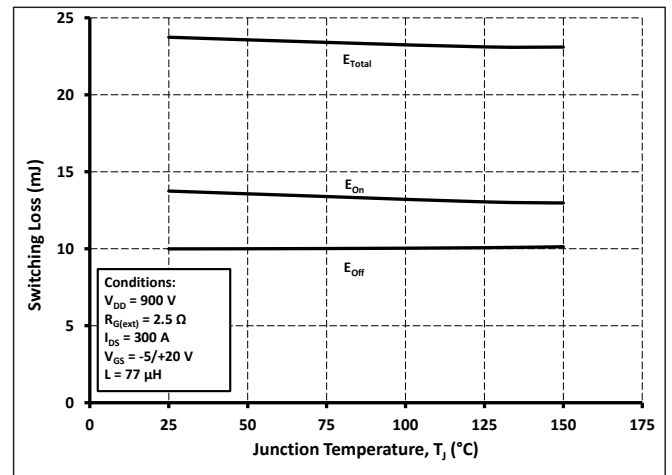


Figure 22. Inductive Switching Energy vs. Temperature

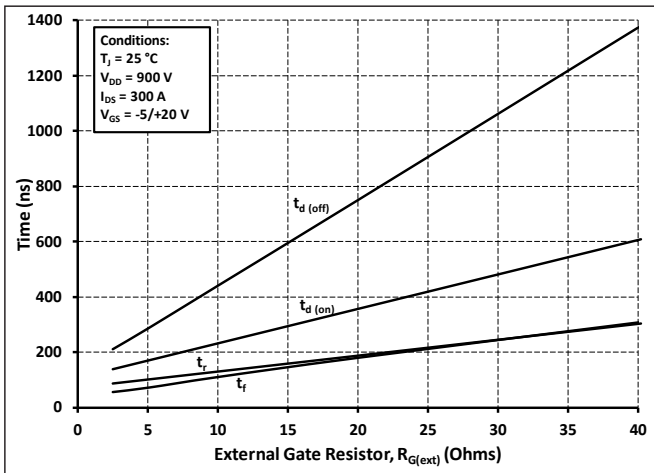


Figure 23. Timing vs. $R_{G(\text{ext})}$

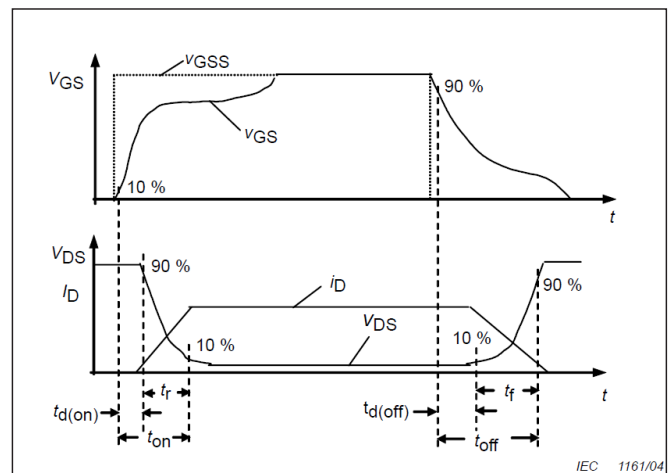


Figure 24. Resistive Switching Time Description



Timing Characteristics

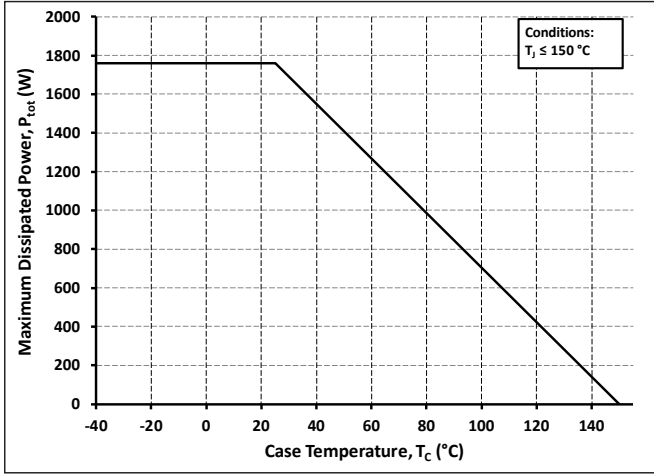


Figure 25. Maximum Power Dissipation (MOSFET) Derating vs. Case Temperature

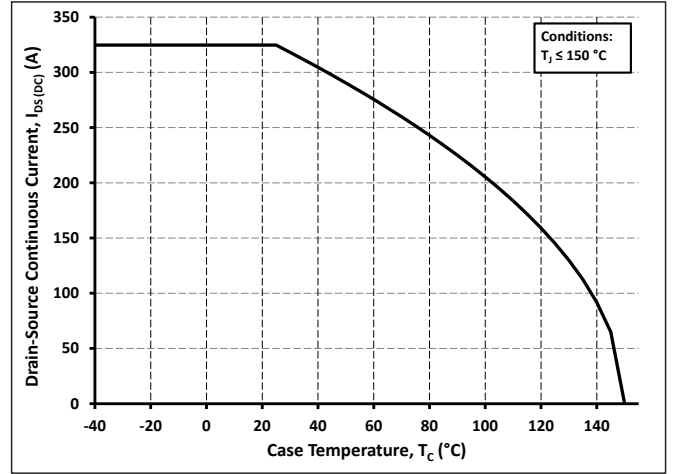


Figure 26. Continuous Drain Current Derating vs. Case Temperature

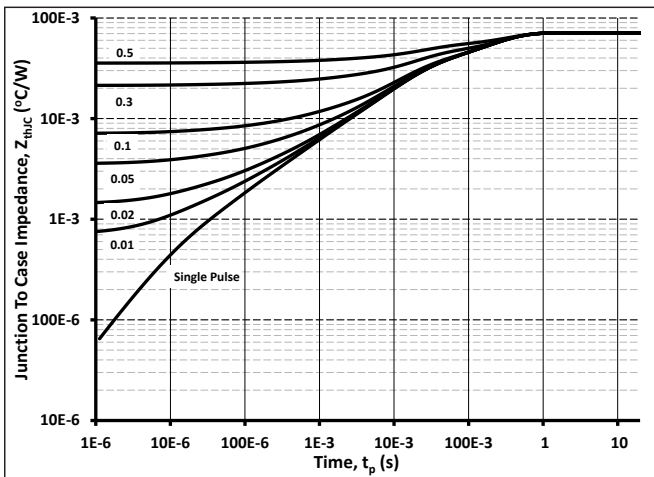


Figure 27. MOSFET Junction to Case Thermal Impedance

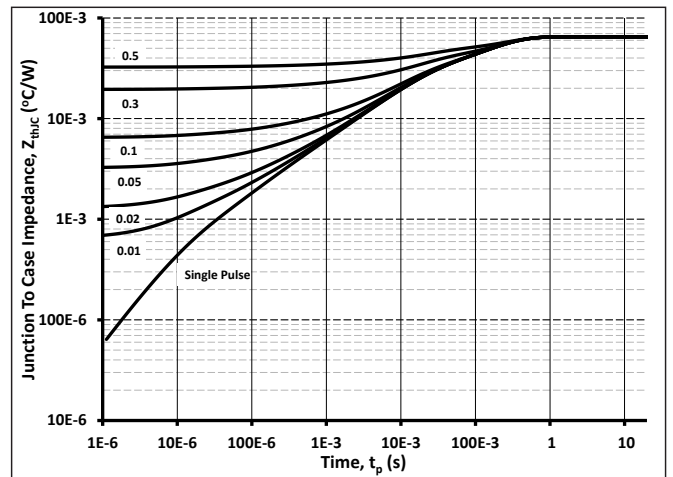


Figure 28. Diode Junction to Case Thermal Impedance

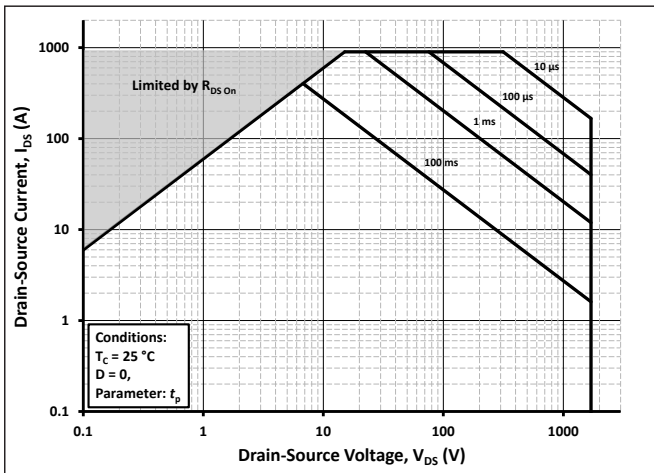
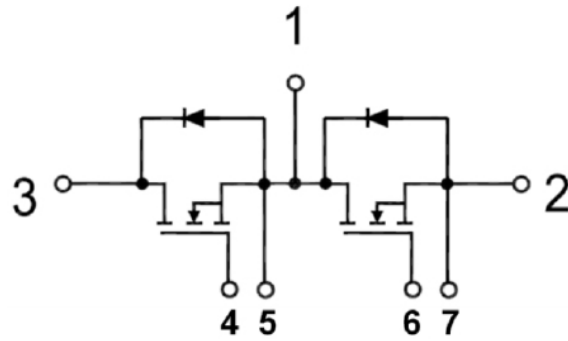


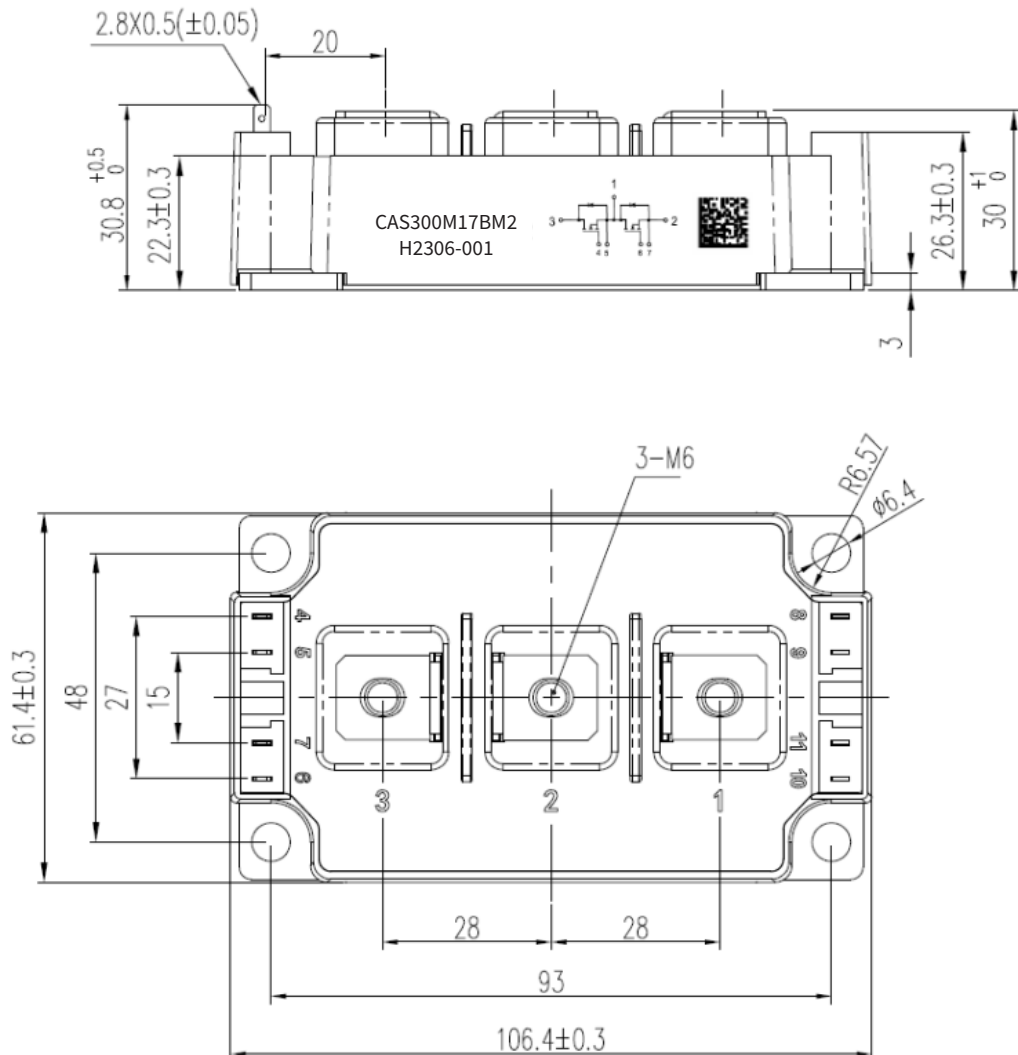
Figure 29. Safe Operating Area



Schematic



Package Dimension (mm)





Supporting Links & Tools

Evaluation Tools & Support

- [KIT-CRD-CIL17N-BM: Dynamic Performance Evaluation Board for the 62 mm Module](#)
- [SpeedFit 2.0 Design Simulator™](#)
- [Technical Support Forum](#)

Dual-Channel Gate Driver Board

- [CGD1700HB2P-BM2: Dual Channel Differential Isolated Half Bridge Gate Driver Board](#)
- [CGD12HB00D: Differential Transceiver Daughter Board Companion Tool for Differential Gate Drivers](#)

Application Notes

- [62 mm Module Mounting Guide](#)
- [62 mm Module Thermal Interface Material Guide](#)



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